

Wiring, Printed - Component

COMPANY

Shenzhen Jia Li Chuang Technology Development Co LTD

27F Olympic building Commercial daily Rd 2 Futian district
Shenzhen, Guangdong 518000 China

E479892

Cond Width			Max Report					Max							
Type	Min	Cond	SS/	Area	date	Surface	Assembly	Solder	Solder	Oper	Meets	C			
	Min	Edge	Thk	DS/	Diam	After	Mount	Process	Process	Limits	Temp	Flame	UL796	T	
	mm	mm	mic	DSO	mm	2022-01-01	Technology	°C	Cycles	°C	sec	°C	Class	DSR	I
Multilayer printed wiring boards															
JLC-1	0.1	0.3	17 Int:102	DS	25.4	No	-	-	-	288	30	130	V-0	All	*
JLC-4(ASP1)	0.1	0.3	12 Int:70	DS	25.4	Yes	Yes	260	2	288	20	130	V-0	All	*
Single layer metal base printed wiring boards															
JLC-8(ASP1)	0.11	0.3	34	SS	25.4	Yes	Yes	260	2	288	20	130	V-0	-	*
JLC-9(ASP1)	0.1	0.3	34	SS	25.4	Yes	Yes	260	2	288	20	100	V-0	All	*
Single layer printed wiring boards															
JLC-2	0.1	0.3	17	DS	25.4	No	-	-	-	288	30	130	V-0	All	*
JLC-3(ASP1) (Note1)	0.1	0.3	12	DS	25.4	Yes	Yes	260	2	288	20	130	V-0	All	*
JLC-5(ASP1)	0.15	0.3	17	DS	25.4	Yes	Yes	260	2	288	20	115	V-0	All	*
JLC-6(ASP1)	0.1	0.3	17	DS	25.4	Yes	Yes	260	2	288	20	130	V-0	All	*
JLC-7(ASP1)	0.1	0.3	17	DS	25.4	Yes	Yes	260	2	288	20	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

(ASP1) - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

(Note1) - When the external copper thk range from 102mic to 140mic, the Min Width and Min edge Width is 0.30mm

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

Last Updated on 2024-03-06

并不是所有出现在本数据库中的公司名称和产品都满足了UL 跟踪检验服务的要求。只有带有 UL 标志的产品，才应该被视为经过UL认证，并满足UL 跟踪检验服务的要求。注意查看产品上的标志。

UL 允许在线认证目录中所含材料的复制遵循以下条件：1.指南信息、装配、构造、设计、系统和/或认证（文件）必须在不篡改任何数据（或图纸）的情况下完整且无误导性地呈现。2.“经 UL 允许从在线认证目录转载”声明必须出现在所摘取材料的邻近位置。此外，转载材料必须包含以下格式的版权声明：“©2024 UL LLC.”